

# DATA SHEET

## **TDA4665** Baseband delay line

Product specification  
Supersedes data of 1995 Oct 30  
File under Integrated Circuits, IC02

1996 Dec 17

## Baseband delay line

## TDA4665

## FEATURES

- Two comb filters, using the switched-capacitor technique, for one line delay time (64  $\mu$ s)
- Adjustment-free application
- No crosstalk between SECAM colour carriers (diaphoty)
- Handles negative or positive colour-difference input signals
- Clamping of AC-coupled input signals ( $\pm(R-Y)$  and  $\pm(B-Y)$ )
- VCO without external components
- 3 MHz internal clock signal derived from a 6 MHz CCO, line-locked by the sandcastle pulse (64  $\mu$ s line)
- Sample-and-hold circuits and low-pass filters to suppress the 3 MHz clock signal
- Addition of delayed and non-delayed output signals
- Output buffer amplifiers
- Comb filtering functions for NTSC colour-difference signals to suppress cross-colour.

## GENERAL DESCRIPTION

The TDA4665 is an integrated baseband delay line circuit with one line delay. It is suitable for decoders with colour-difference signal outputs  $\pm(R-Y)$  and  $\pm(B-Y)$ .

## QUICK REFERENCE DATA

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
$V_{P1}$	analog supply voltage (pin 9)	4.5	5	6	V
$V_{P2}$	digital supply voltage (pin 1)	4.5	5	6	V
$I_{P(\text{tot})}$	total supply current	–	5.5	7.0	mA
$V_{i(\text{p-p})}$	$\pm(R-Y)$ input signal PAL/NTSC (peak-to-peak value; pin 16)	–	525	–	mV
	$\pm(B-Y)$ input signal PAL/NTSC (peak-to-peak value; pin 14)	–	665	–	mV
	$\pm(R-Y)$ input signal SECAM (peak-to-peak value; pin 16)	–	1.05	–	V
	$\pm(B-Y)$ input signal SECAM (peak-to-peak value; pin 14)	–	1.33	–	V
$G_v$	gain $V_o / V_i$ of colour-difference output signals				
	$V_{11} / V_{16}$ for PAL and NTSC	5.3	5.8	6.3	dB
	$V_{12} / V_{14}$ for PAL and NTSC	5.3	5.8	6.3	dB
	$V_{11} / V_{16}$ for SECAM	–0.6	–0.1	+0.4	dB
	$V_{12} / V_{14}$ for SECAM	–0.6	–0.1	+0.4	dB

## ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
TDA4665	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
TDA4665T	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1

Baseband delay line

TDA4665

BLOCK DIAGRAM

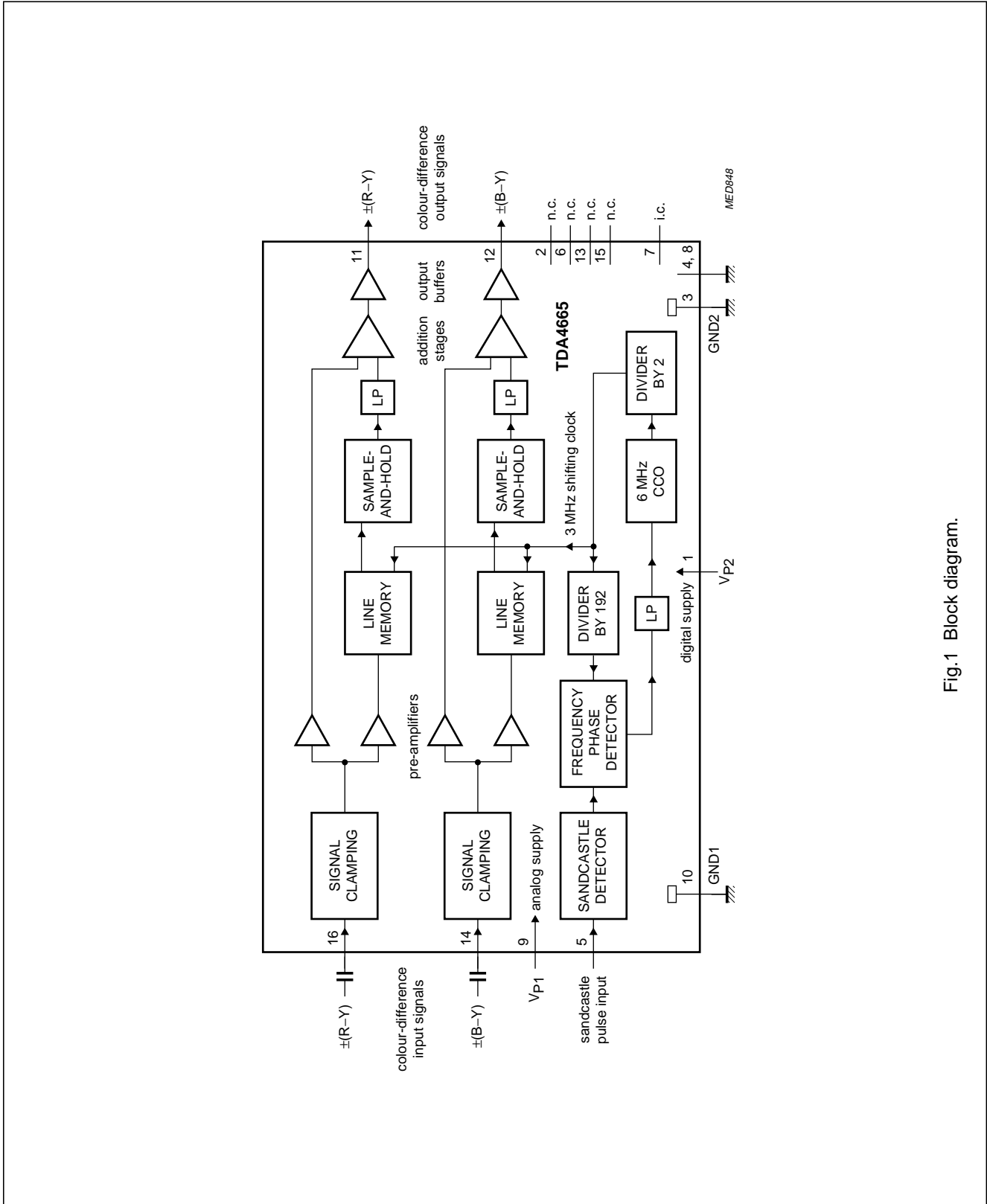


Fig.1 Block diagram.

Baseband delay line

TDA4665

PINNING

SYMBOL	PIN	DESCRIPTION
V <sub>P2</sub>	1	+5 V supply voltage for digital part
n.c.	2	not connected
GND2	3	ground for digital part (0 V)
i.c.	4	internally connected
SAND	5	sandcastle pulse input
n.c.	6	not connected
i.c.	7	internally connected
i.c.	8	internally connected
V <sub>P1</sub>	9	+5 V supply voltage for analog part
GND1	10	ground for analog part (0 V)
V <sub>o(R-Y)</sub>	11	±(R-Y) output signal
V <sub>o(B-Y)</sub>	12	±(B-Y) output signal
n.c.	13	not connected
V <sub>i(B-Y)</sub>	14	±(B-Y) input signal
n.c.	15	not connected
V <sub>i(R-Y)</sub>	16	±(R-Y) input signal

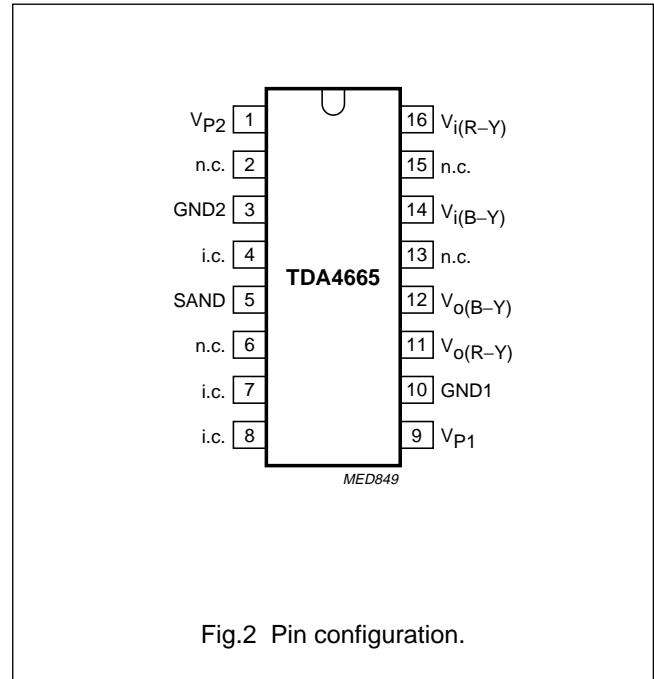


Fig.2 Pin configuration.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134). Ground pins 3 and 10 connected together.

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V <sub>P1</sub>	analog supply voltage (pin 9)	-0.5	+7	V
V <sub>P2</sub>	digital supply voltage (pin 1)	-0.5	+7	V
V <sub>5</sub>	voltage on pin 5	-0.5	V <sub>P</sub> + 1.0	V
V <sub>n</sub>	voltage on pins 11, 12, 14 and 16	-0.5	V <sub>P</sub>	V
T <sub>stg</sub>	storage temperature	-25	+150	°C
T <sub>amb</sub>	operating ambient temperature	0	70	°C
V <sub>ESD</sub>	electrostatic handling for all pins; note 1	-	±500	V

Note

1. Equivalent to discharging a 200 pF capacitor through a 0 Ω series resistor.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient in free air		
	SOT38-4	75	K/W
	SOT109-1	220	K/W

## Baseband delay line

TDA4665

**CHARACTERISTICS**

$V_P = 5.0$  V; input signals as specified in characteristics with 75% colour bars; super-sandcastle frequency of 15.625 kHz;  $T_{amb} = 25$  °C; measurements taken in Fig.3; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Supply</b>						
$V_{P1}$	analog supply voltage (pin 9)		4.5	5	6	V
$V_{P2}$	digital supply voltage (pin 1)		4.5	5	6	V
$I_{P1}$	analog supply current		–	4.8	6.0	mA
$I_{P2}$	digital supply current		–	0.7	1.0	mA
<b>Colour-difference input signals</b>						
$V_{i(p-p)}$	input signal (peak-to-peak value) ±(R–Y) PAL and NTSC (pin 16) ±(B–Y) PAL and NTSC (pin 14) ±(R–Y) SECAM (pin 16) ±(B–Y) SECAM (pin 14)	note 1	–	525 665 1.05 1.33	–	mV mV V V
$V_{i(max)(p-p)}$	maximum symmetrical input signal (peak-to-peak value) ±(R–Y) or ±(B–Y) for PAL and NTSC ±(R–Y) or ±(B–Y) for SECAM	before clipping before clipping	1 2	– –	– –	V V
$R_{14, 16}$	input resistance during clamping		–	–	40	kΩ
$C_{14, 16}$	input capacitance		–	–	10	pF
$V_{14, 16}$	input clamping voltage	proportional to $V_P$	1.3	1.5	1.7	V
<b>Colour-difference output signals</b>						
$V_{o(p-p)}$	output signal (peak-to-peak value) ±(R–Y) on pin 11 ±(B–Y) on pin 12	all standards all standards	–	1.05 1.33	–	V V
$V_{11}/V_{12}$	ratio of output amplitudes at equal input signals	$V_{i(14,16)(p-p)} = 1.33$ V	–0.4	0	+0.4	dB
$V_{11, 12}$	DC output voltage	proportional to $V_P$	2.5	2.9	3.3	V
$R_{11, 12}$	output resistance		–	330	400	Ω
$G_v$	gain for PAL and NTSC	ratio $V_o/V_i$	5.3	5.8	6.3	dB
	gain for SECAM	ratio $V_o/V_i$	–0.6	–0.1	+0.4	dB
$V_n/V_{n+1}$	ratio of delayed to non-delayed output signals (pins 11 and 12)	$V_{i(14,16)(p-p)} = 1.33$ V; SECAM signals	–0.1	0	+0.1	dB
$V_{n(rms)}$	noise voltage (RMS value; pins 11 and 12)	$V_{i(14,16)} = 0$ V; note 2	–	–	1.2	mV
$V_{(11,12)(p-p)}$	unwanted signals (line-locked) (peak-to-peak value)	$V_{i(14,16)} = 0$ V; active video; $R_S = 300$ Ω	–	–	5	mV
	meander		–	–	10	mV
	spikes		–	–	–	–
$S/N(W)$	weighted signal-to-noise ratio (pins 11 and 12)	$V_{o(p-p)} = 1$ V; note 2	–	54	–	dB
$\Delta t_d$	time difference between non-delayed and delayed output signals (pins 11 and 12)		63.94	64	64.06	μs

## Baseband delay line

## TDA4665

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$t_d$	delay of non-delayed signals		40	60	80	ns
$t_{tr}$	transient time of delayed signal on pins 11 respectively 12	300 ns transient of SECAM signal	–	350	–	ns
	transient time of non-delayed signal on pins 11 respectively 12	300 ns transient of SECAM signal	–	320	–	ns
<b>Sandcastle pulse input (pin 5)</b>						
$f_{BK}$	burst-key frequency/sandcastle frequency		14.2	15.625	17.0	kHz
$V_5$	top pulse voltage	note 3	4.0	–	$V_P + 1.0$	V
$V_{slice}$	internal slicing level		$V_5 - 1.0$	–	$V_5 - 0.5$	V
$I_5$	input current		–	–	10	$\mu A$
$C_5$	input capacitance		–	–	10	pF

**Notes**

1. For SECAM the signal must be blanked line-sequentially. The blanking level must be equal to the non-colour signal. For SECAM, PAL and NTSC the input signal must be equal to the non-colour signal during the internal clamping of TDA4665 (3 to 1  $\mu s$  before the leading edge of the top pulse of  $V_5$ ).
2. Noise voltage at  $f = 10$  kHz to 1 MHz;  $R_S < 300 \Omega$ .
3. The leading edge of the burst-key pulse or top pulse is used for timing.

Baseband delay line

TDA4665

APPLICATION INFORMATION

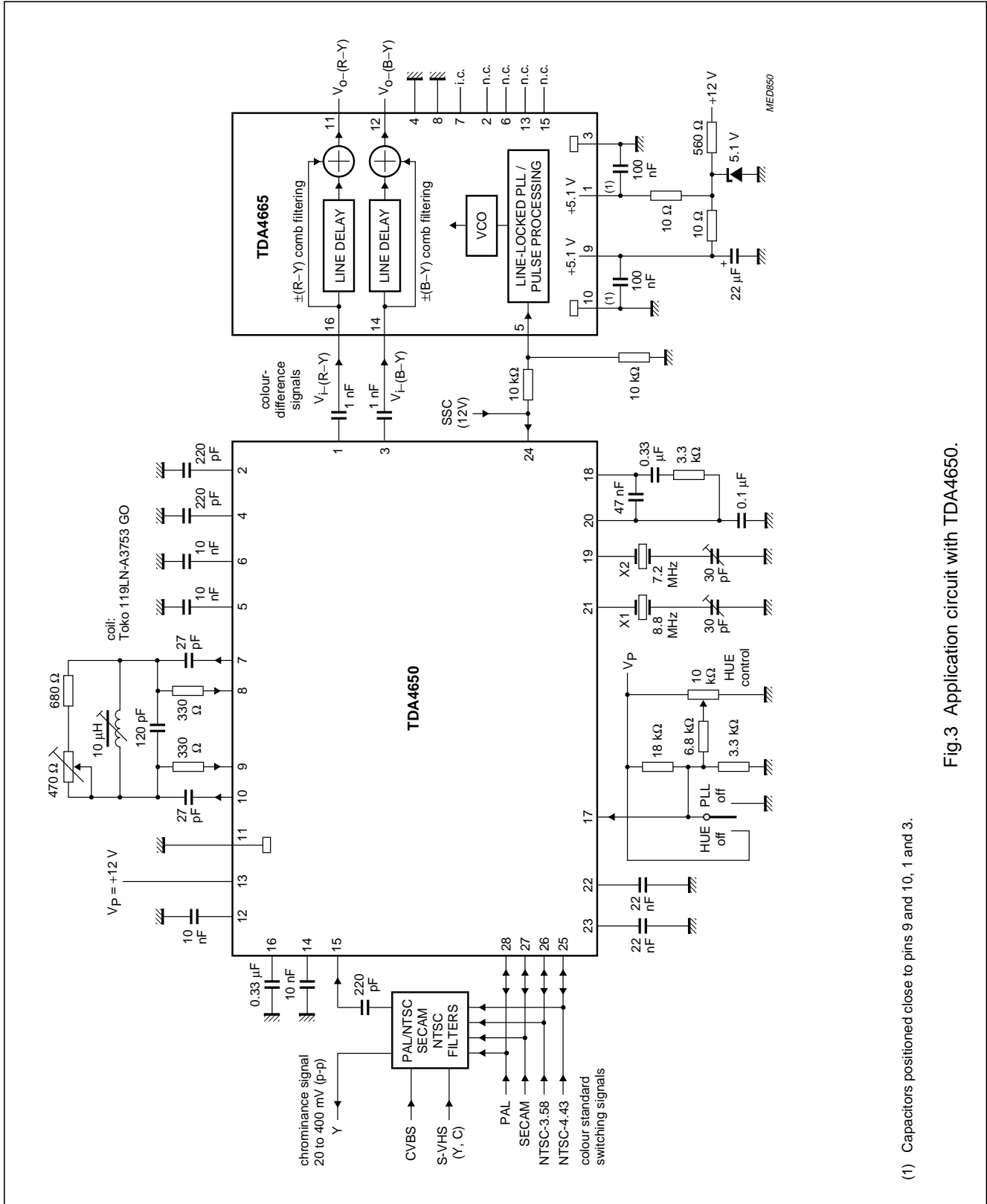


Fig.3 Application circuit with TDA4650.

(1) Capacitors positioned close to pins 9 and 10, 1 and 3.

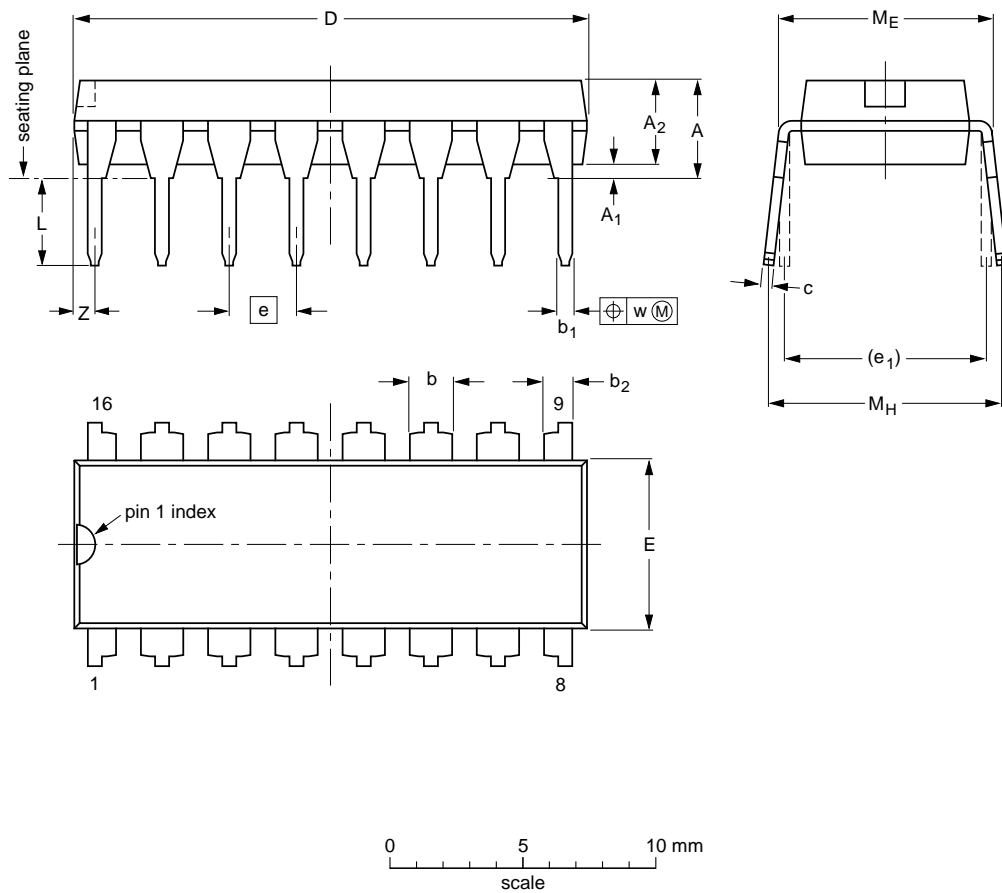
Baseband delay line

TDA4665

PACKAGE OUTLINES

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	b <sub>2</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.030

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT38-4					92-11-17 95-01-14

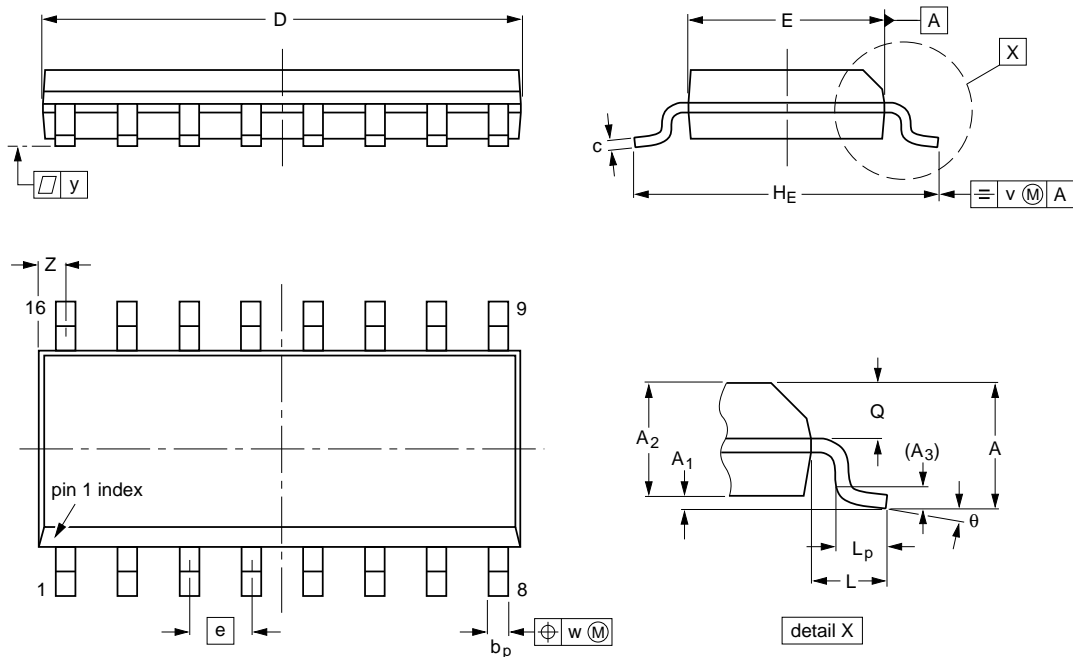


Baseband delay line

TDA4665

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.0098 0.0039	0.057 0.049	0.01	0.019 0.014	0.0098 0.0075	0.39 0.38	0.16 0.15	0.050	0.24 0.23	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT109-1	076E07S	MS-012AC			91-08-13 95-01-23

## Baseband delay line

TDA4665

### SOLDERING

#### Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "IC Package Databook" (order code 9398 652 90011).

#### DIP

##### SOLDERING BY DIPPING OR BY WAVE

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ( $T_{stg\ max}$ ). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

##### REPAIRING SOLDERED JOINTS

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

#### SO

##### REFLOW SOLDERING

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

##### WAVE SOLDERING

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

##### REPAIRING SOLDERED JOINTS

Fix the component by first soldering two diagonally-opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

## Baseband delay line

TDA4665

**DEFINITIONS**

<b>Data sheet status</b>	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
<b>Limiting values</b>	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
<b>Application information</b>	
Where application information is given, it is advisory and does not form part of the specification.	

**LIFE SUPPORT APPLICATIONS**

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

# Philips Semiconductors – a worldwide company

**Argentina:** see South America

**Australia:** 34 Waterloo Road, NORTH RYDE, NSW 2113,  
Tel. +61 2 9805 4455, Fax. +61 2 9805 4466

**Austria:** Computerstr. 6, A-1101 WIEN, P.O. Box 213,  
Tel. +43 1 60 101, Fax. +43 1 60 101 1210

**Belarus:** Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6,  
220050 MINSK, Tel. +375 172 200 733, Fax. +375 172 200 773

**Belgium:** see The Netherlands

**Brazil:** see South America

**Bulgaria:** Philips Bulgaria Ltd., Energoproject, 15th floor,  
51 James Bourchier Blvd., 1407 SOFIA,  
Tel. +359 2 689 211, Fax. +359 2 689 102

**Canada:** PHILIPS SEMICONDUCTORS/COMPONENTS,  
Tel. +1 800 234 7381

**China/Hong Kong:** 501 Hong Kong Industrial Technology Centre,  
72 Tat Chee Avenue, Kowloon Tong, HONG KONG,  
Tel. +852 2319 7888, Fax. +852 2319 7700

**Colombia:** see South America

**Czech Republic:** see Austria

**Denmark:** Prags Boulevard 80, PB 1919, DK-2300 COPENHAGEN S,  
Tel. +45 32 88 2636, Fax. +45 31 57 1949

**Finland:** Sinikalliontie 3, FIN-02630 ESPOO,  
Tel. +358 9 615800, Fax. +358 9 61580/xxx

**France:** 4 Rue du Port-aux-Vins, BP317, 92156 SURESNES Cedex,  
Tel. +33 1 40 99 6161, Fax. +33 1 40 99 6427

**Germany:** Hammerbrookstraße 69, D-20097 HAMBURG,  
Tel. +49 40 23 53 60, Fax. +49 40 23 536 300

**Greece:** No. 15, 25th March Street, GR 17778 TAVROS/ATHENS,  
Tel. +30 1 4894 339/239, Fax. +30 1 4814 240

**Hungary:** see Austria

**India:** Philips INDIA Ltd, Shivsagar Estate, A Block, Dr. Annie Besant Rd.  
Worli, MUMBAI 400 018, Tel. +91 22 4938 541, Fax. +91 22 4938 722

**Indonesia:** see Singapore

**Ireland:** Newstead, Clonskeagh, DUBLIN 14,  
Tel. +353 1 7640 000, Fax. +353 1 7640 200

**Israel:** RAPAC Electronics, 7 Kehilat Saloniki St, TEL AVIV 61180,  
Tel. +972 3 645 0444, Fax. +972 3 649 1007

**Italy:** PHILIPS SEMICONDUCTORS, Piazza IV Novembre 3,  
20124 MILANO, Tel. +39 2 6752 2531, Fax. +39 2 6752 2557

**Japan:** Philips Bldg 13-37, Kohnan 2-chome, Minato-ku, TOKYO 108,  
Tel. +81 3 3740 5130, Fax. +81 3 3740 5077

**Korea:** Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL,  
Tel. +82 2 709 1412, Fax. +82 2 709 1415

**Malaysia:** No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR,  
Tel. +60 3 750 5214, Fax. +60 3 757 4880

**Mexico:** 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,  
Tel. +9-5 800 234 7381

**Middle East:** see Italy

**Netherlands:** Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,  
Tel. +31 40 27 82785, Fax. +31 40 27 88399

**New Zealand:** 2 Wagener Place, C.P.O. Box 1041, AUCKLAND,  
Tel. +64 9 849 4160, Fax. +64 9 849 7811

**Norway:** Box 1, Manglerud 0612, OSLO,  
Tel. +47 22 74 8000, Fax. +47 22 74 8341

**Philippines:** Philips Semiconductors Philippines Inc.,  
106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI,  
Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

**Poland:** Ul. Lukiska 10, PL 04-123 WARSZAWA,  
Tel. +48 22 612 2831, Fax. +48 22 612 2327

**Portugal:** see Spain

**Romania:** see Italy

**Russia:** Philips Russia, Ul. Usatcheva 35A, 119048 MOSCOW,  
Tel. +7 095 247 9145, Fax. +7 095 247 9144

**Singapore:** Lorong 1, Toa Payoh, SINGAPORE 1231,  
Tel. +65 350 2538, Fax. +65 251 6500

**Slovakia:** see Austria

**Slovenia:** see Italy

**South Africa:** S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale,  
2092 JOHANNESBURG, P.O. Box 7430 Johannesburg 2000,  
Tel. +27 11 470 5911, Fax. +27 11 470 5494

**South America:** Rua do Rocio 220, 5th floor, Suite 51,  
04552-903 São Paulo, SÃO PAULO - SP, Brazil,  
Tel. +55 11 821 2333, Fax. +55 11 829 1849

**Spain:** Balmes 22, 08007 BARCELONA,  
Tel. +34 3 301 6312, Fax. +34 3 301 4107

**Sweden:** Kottbygatan 7, Akalla, S-16485 STOCKHOLM,  
Tel. +46 8 632 2000, Fax. +46 8 632 2745

**Switzerland:** Allmendstrasse 140, CH-8027 ZÜRICH,  
Tel. +41 1 488 2686, Fax. +41 1 481 7730

**Taiwan:** PHILIPS TAIWAN Ltd., 23-30F, 66,  
Chung Hsiao West Road, Sec. 1, P.O. Box 22978,  
TAIPEI 100, Tel. +886 2 382 4443, Fax. +886 2 382 4444

**Thailand:** PHILIPS ELECTRONICS (THAILAND) Ltd.,  
209/2 Sanpavuth-Bangna Road Prakanong, BANGKOK 10260,  
Tel. +66 2 745 4090, Fax. +66 2 398 0793

**Turkey:** Talatpasa Cad. No. 5, 80640 GÜLTEPE/ISTANBUL,  
Tel. +90 212 279 2770, Fax. +90 212 282 6707

**Ukraine:** PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7,  
252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

**United Kingdom:** Philips Semiconductors Ltd., 276 Bath Road, Hayes,  
MIDDLESEX UB3 5BX, Tel. +44 181 730 5000, Fax. +44 181 754 8421

**United States:** 811 East Arques Avenue, SUNNYVALE, CA 94088-3409,  
Tel. +1 800 234 7381

**Uruguay:** see South America

**Vietnam:** see Singapore

**Yugoslavia:** PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD,  
Tel. +381 11 625 344, Fax. +381 11 635 777

**For all other countries apply to:** Philips Semiconductors, Marketing & Sales Communications,  
Building BE-p, P.O. Box 218, 5600 MD EINDHOVEN, The Netherlands, Fax. +31 40 27 24825

**Internet:** <http://www.semiconductors.philips.com>

© Philips Electronics N.V. 1996

SCA52

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Printed in The Netherlands

537021/1200/03/pp12

Date of release: 1996 Dec 17

Document order number: 9397 750 01376

*Let's make things better.*

**Philips**  
Semiconductors



**PHILIPS**